

3-V TO 5.5-V MULTICHANNEL RS-232 1-Mbit/s LINE DRIVER/RECEIVER

 Check for Samples: [MAX3237E](#)

FEATURES

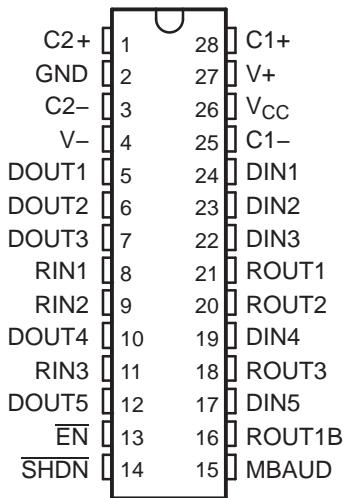
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates From 250 kbit/s to 1 Mbit/s
- Low Standby Current . . . 1 μ A Typical
- External Capacitors . . . 4 \times 0.1 μ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Designed to Be Interchangeable With Maxim MAX3237E
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

- ESD Protection for RS-232 I/O Pins
 - ± 15 kV – Human-Body Model (HBM)
 - ± 8 kV – IEC61000-4-2, Contact Discharge
 - ± 15 kV – IEC61000-4-2, Air-Gap Discharge

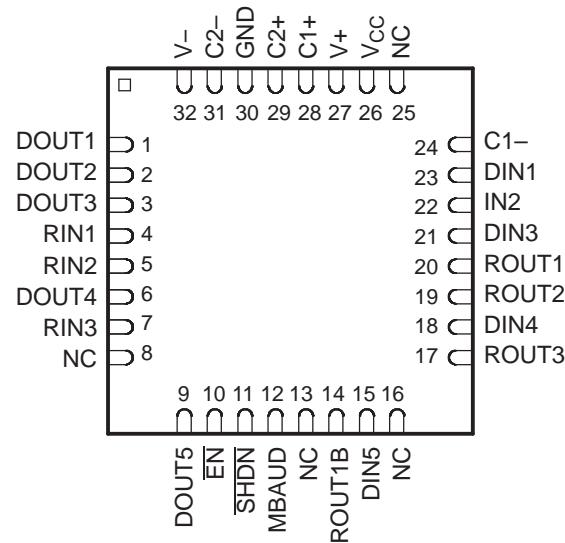
APPLICATIONS

- Battery-Powered, Hand-Held, and Portable Equipment
- PDAs and Palmtop PCs
- Notebooks, Sub-Notebooks, and Laptops
- Digital Cameras
- Mobile Phones and Wireless Devices

DB, DW, OR PW PACKAGE
(TOP VIEW)



QFN PACKAGE
(TOP VIEW)



DESCRIPTION

The MAX3237E consists of five line drivers, three line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. This device operates at data signaling rates of 250 kbit/s in normal operating mode (MBAUD = GND) and 1Mbit/s when MBAUD = V_{CC} . The driver output slew rate is a maximum of 30 V/ μ s.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

The MAX3237E transmitters are disabled and the outputs are forced into high-impedance state when the device is in shutdown mode (SHDN = GND) and the supply current falls to less than 1 μ A. Also, during shutdown, the onboard charge pump is disabled; V+ is lowered to V_{CC}, and V– is raised toward GND. Receiver outputs also can be placed in the high-impedance state by setting enable (EN) high. ROUT1B remains active all the time, regardless of the EN and SHDN condition.

The MAX3237EC is characterized for operation from 0°C to 70°C. The MAX3237EI is characterized for operation from –40°C to 85°C.

AVAILABLE OPTIONS⁽¹⁾

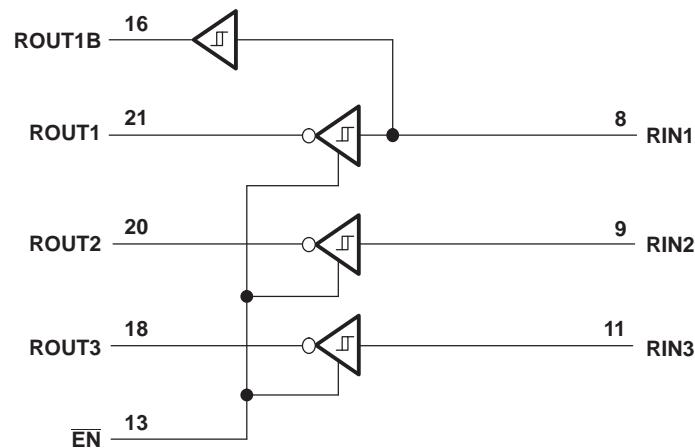
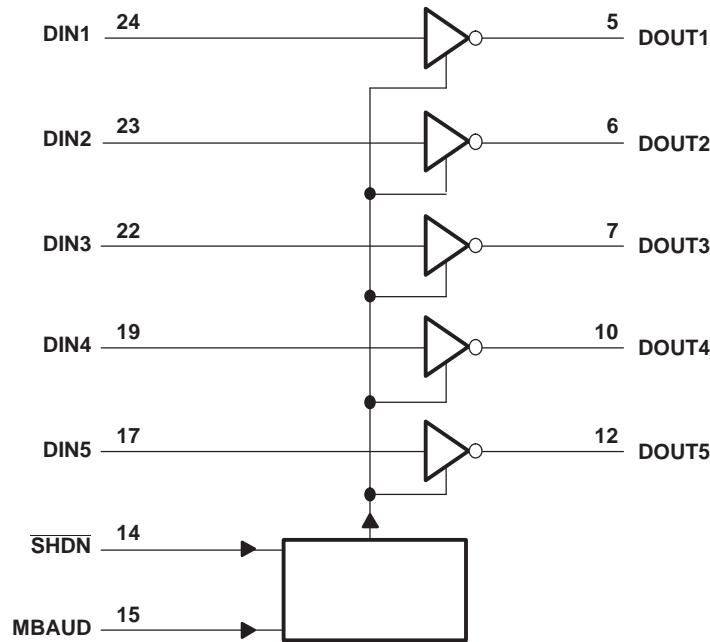
T _A	PACKAGED DEVICES ⁽²⁾
0°C to 70°C	MAX3237ECDBR
	MAX3237ECPWR
	MAX3237ECRHBR (QFN package)
	MAX3237ECDWR
–40°C to 85°C	MAX3237EIDBR
	MAX3237EIPWR
	MAX3237EIRHBR (QFN package)
	MAX3237EIDWR

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

Table 1. FUNCTION TABLE

INPUTS		OUTPUTS		
SHDN	EN	DOUT	ROUT	ROUT1B
0	0	Z ⁽¹⁾	Active	Active
0	1	Z ⁽¹⁾	Z ⁽¹⁾	Active
1	0	Active	Active	Active
1	1	Active	Z ⁽¹⁾	Active

- (1) Z = high impedance (off)

LOGIC DIAGRAM (POSITIVE LOGIC)


ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range ⁽²⁾		-0.3	6	V
V_+	Positive-output supply voltage range ⁽²⁾		-0.3	7	V
V_-	Negative-output supply voltage range ⁽²⁾		0.3	-7	V
$V_+ - V_-$	Supply voltage difference ⁽²⁾			13	V
V_I	Input voltage range	Driver (\overline{SHDN} , $MBAUD$, \overline{EN})	-0.3	6	V
		Receiver	-25	25	
V_O	Output voltage range	Driver	-13.2	13.2	V
		Receiver	-0.3	$V_{CC} + 0.3$	
	Short-circuit duration	DOUT to GND	Unlimited		
θ_{JA}	Package thermal impedance ⁽³⁾			62	°C/W
T_{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to network GND.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾See [Figure 5](#)

			MIN	NOM	MAX	UNIT
Supply voltage		$V_{CC} = 3.3$ V	3	3.3	3.6	V
		$V_{CC} = 5$ V	4.5	5	5.5	
V_{IH}	Driver and control high-level input voltage	$V_{CC} = 3.3$ V	2	5.5	5.5	V
		$V_{CC} = 5$ V	2.4	5.5	5.5	
V_{IL}	Driver and control low-level input voltage	DIN, \overline{SHDN} , $MBAUD$, \overline{EN}	0	0.8	0.8	V
V_I	Receiver input voltage		-25	25	25	V
T_A	Operating free-air temperature	MAX3237EC	0	70	70	°C
		MAX3237EI	-40	85	85	

(1) Test conditions are $C1-C4 = 0.1 \mu F$ at $V_{CC} = 3$ V to 5 V.

ELECTRICAL CHARACTERISTICS⁽¹⁾over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
I_I	Input leakage current	DIN, \overline{SHDN} , $MBAUD$, \overline{EN}		9	18	μA
I_{CC}	Supply current ($T_A = 25^\circ C$)	No load, $\overline{SHDN} = V_{CC}$		0.5	2	mA
		$\overline{SHDN} = GND$		1	10	μA
		$\overline{SHDN} = R_{IN} = GND$, $DIN = GND$ or V_{CC}		10	300	nA

(1) Test conditions are $C1-C4 = 0.1 \mu F$ at $V_{CC} = 3$ V to 5 V.

(2) All typical values are at $V_{CC} = 3.3$ V or $V_{CC} = 5$ V, and $T_A = 25^\circ C$.

DRIVER SECTION ELECTRICAL CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH}	High-level output voltage DOUT at $R_L = 3 \text{ k}\Omega$ to GND, DIN = GND	5	5.4		V
V_{OL}	Low-level output voltage DOUT at $R_L = 3 \text{ k}\Omega$ to GND, DIN = V_{CC}	-5	-5.4		V
I_{IH}	High-level input current $V_I = V_{CC}$		± 0.01	± 1	μA
I_{IL}	Low-level input current V_I at GND		± 0.01	± 1	μA
I_{OS}	Short-circuit output current ⁽³⁾ $V_{CC} = 3.6 \text{ V}$ or 3.3 V , $V_O = 0 \text{ V}$			± 60	mA
r_o	V_{CC} , V_+ , and $V_- = 0 \text{ V}$, $V_O = \pm 2 \text{ V}$	300	50k		Ω

(1) Test conditions are $C1-C4 = 0.1 \mu\text{F}$ at $V_{CC} = 3 \text{ V}$ to 5 V .

(2) All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

DRIVER SECTION SWITCHING CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT	
Maximum data rate	$C_L = 1000 \text{ pF}$, MBAUD = GND	250			kbit/s	
	$C_L = 1000 \text{ pF}$, $V_{CC} = 4.5 \text{ V}$ to 5.5 V , MBAUD = V_{CC}	1000				
	$C_L = 250 \text{ pF}$, $V_{CC} = 3 \text{ V}$ to 4.5 V , MBAUD = V_{CC}	1000				
$t_{sk(p)}$	Pulse skew ⁽³⁾ $C_L = 150 \text{ pF}$ to 2500 pF , $R_L = 3 \text{ k}\Omega$ to $7 \text{ k}\Omega$, MBAUD = V_{CC} or GND, See Figure 2		100		ns	
SR(tr)	$V_{CC} = 3.3 \text{ V}$, $R_L = 3 \text{ k}\Omega$ to $7 \text{ k}\Omega$, $T_A = 25^\circ\text{C}$	$C_L = 150 \text{ pF}$ to 1000 pF	MBAUD = GND	6	30	V/ μs
			MBAUD = V_{CC}	24	150	
		$C_L = 150 \text{ pF}$ to 2500 pF ,	MBAUD = GND	4	30	

(1) Test conditions are $C1-C4 = 0.1 \mu\text{F}$ at $V_{CC} = 3 \text{ V}$ to 5 V .

(2) All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

RECEIVER SECTION ELECTRICAL CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH} High-level output voltage	$I_{OH} = -1 \text{ mA}$	$V_{CC} - 0.6$	$V_{CC} - 0.1$		V
V_{OL} Low-level output voltage	$I_{OL} = 1 \text{ mA}$			0.4	V
V_{IT+} Positive-going input threshold voltage	$V_{CC} = 3.3 \text{ V}$		1.5	2.4	V
	$V_{CC} = 5 \text{ V}$		2	2.4	
V_{IT-} Negative-going input threshold voltage	$V_{CC} = 3.3 \text{ V}$	0.6	1.1		V
	$V_{CC} = 5 \text{ V}$	0.8	1.5		
V_{hys} Input hysteresis ($V_{IT+} - V_{IT-}$)			0.5		V
I_{oz} Output leakage current	$\overline{EN} = V_{CC}$		± 0.05	± 10	μA
r_i Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	$\text{k}\Omega$

(1) Test conditions are $C1-C4 = 0.1 \mu\text{F}$ at $V_{CC} = 3 \text{ V to } 5 \text{ V}$.

(2) All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

RECEIVER SECTION SWITCHING CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP ⁽²⁾	UNIT
t_{PLH} Propagation delay time, low- to high-level output	$C_L = 150 \text{ pF}$, See Figure 3	150	ns
t_{PHL} Propagation delay time, high- to low-level output	$C_L = 150 \text{ pF}$, See Figure 3	150	ns
t_{en} Output enable time	$C_L = 150 \text{ pF}$, $R_L = 3 \text{ k}\Omega$, See Figure 4	2.6	μs
t_{dis} Output disable time	$C_L = 150 \text{ pF}$, $R_L = 3 \text{ k}\Omega$, See Figure 4	2.4	μs
$t_{sk(p)}$ Pulse skew ⁽³⁾	See Figure 3	50	ns

(1) Test conditions are $C1-C4 = 0.1 \mu\text{F}$ at $V_{CC} = 3 \text{ V to } 5 \text{ V}$.

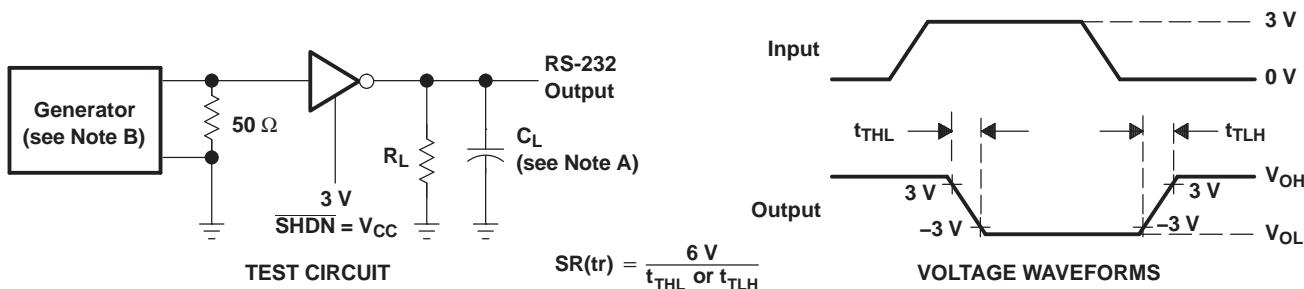
(2) All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

ESD PROTECTION

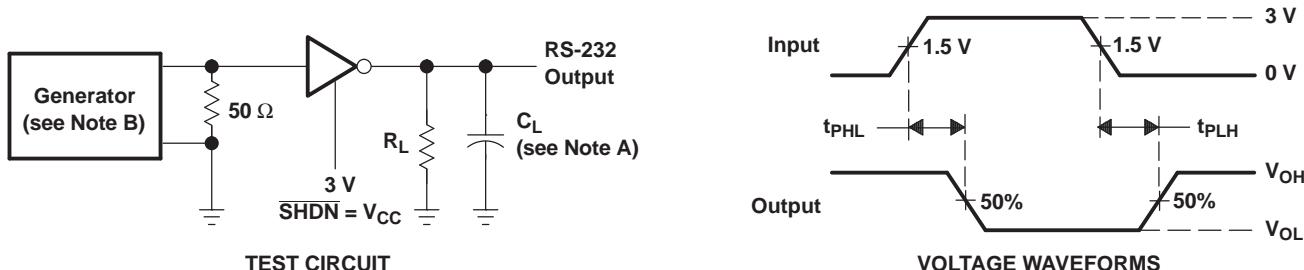
PIN	TEST CONDITIONS	TYP	UNIT
DOUT, RIN	HBM	± 15	kV
	IEC61000-4-2, Contact Discharge	± 8	
	IEC61000-4-2, Air-Gap Discharge	± 15	

PARAMETER MEASUREMENT INFORMATION



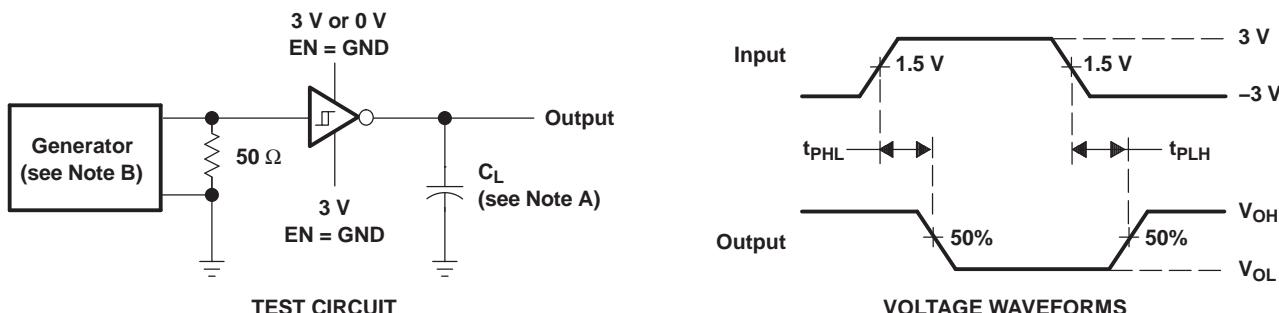
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

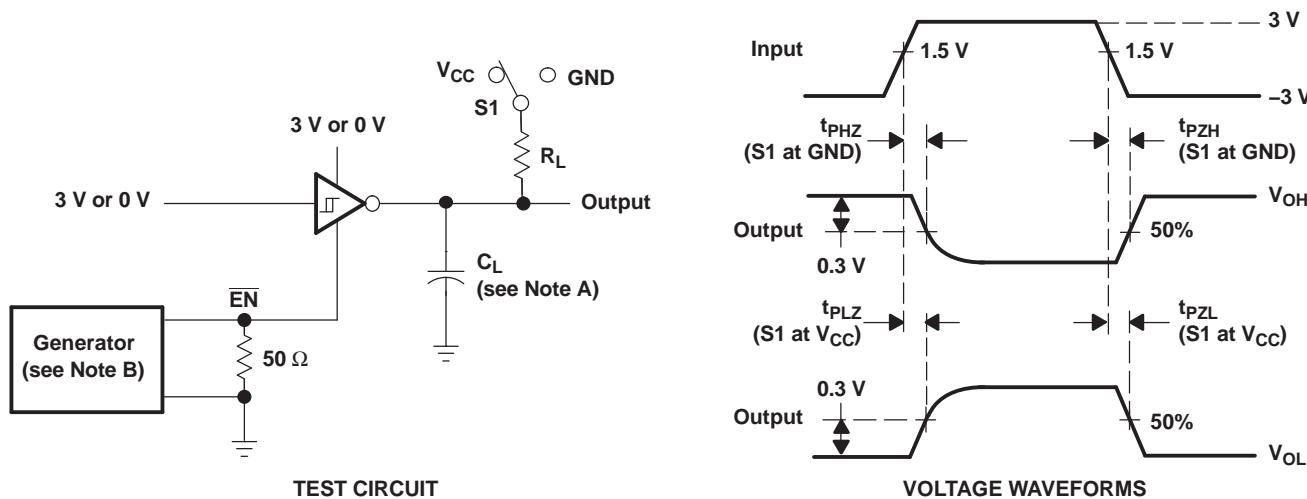
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

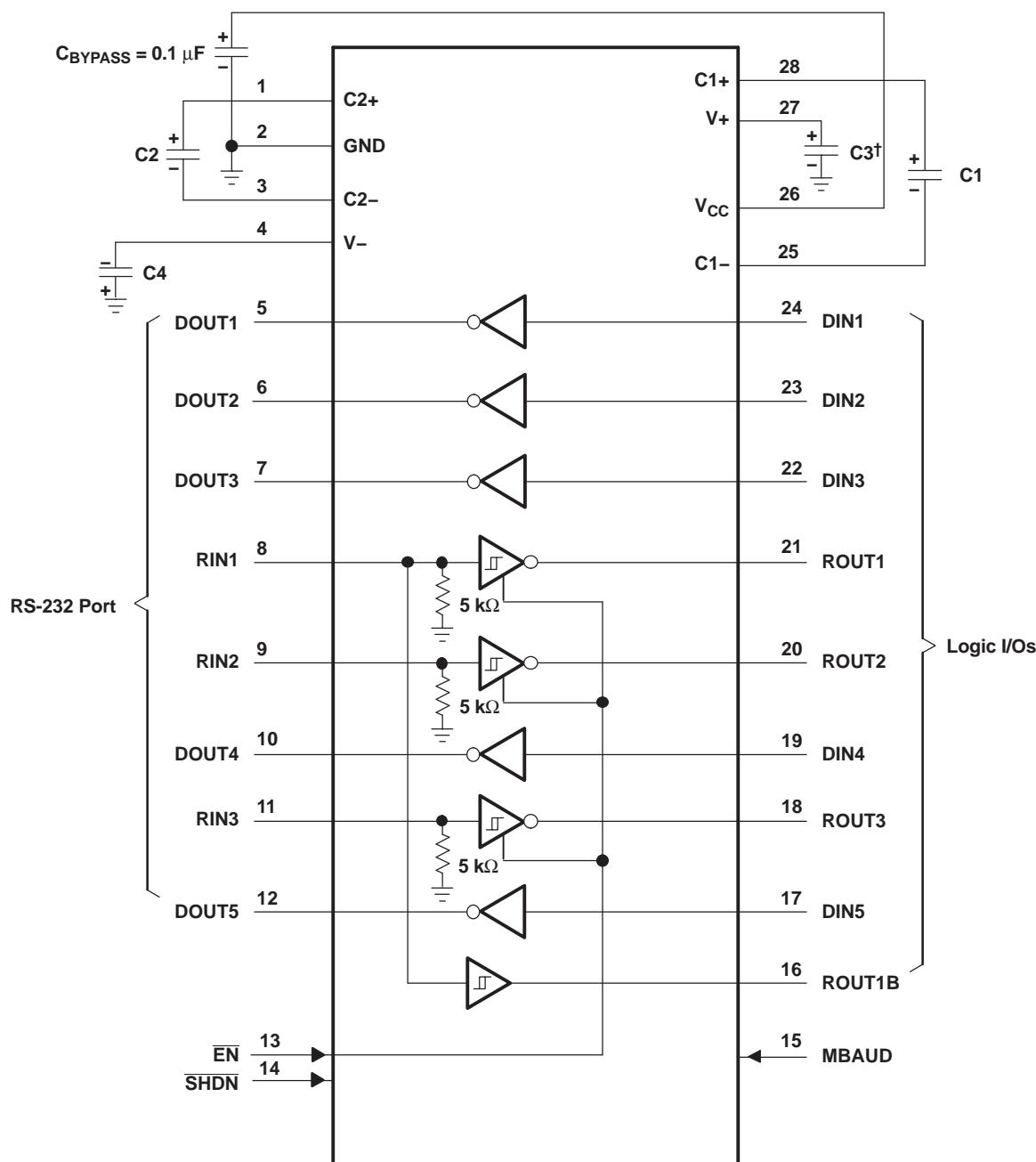
Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION (continued)



- NOTES:
- C_L includes probe and jig capacitance.
 - The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 4. Receiver Enable and Disable Times

APPLICATION INFORMATION


NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V _{CC}	C1	C2, C3, and C4
3.3 V \pm 0.15 V	0.1 μ F	0.1 μ F
3.3 V \pm 0.3 V	0.22 μ F	0.22 μ F
5 V \pm 0.5 V	0.047 μ F	0.33 μ F
3 V to 5.5 V	0.22 μ F	1 μ F

Figure 5. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MAX3237ECDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECDBG4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECDBRG4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECDW	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECDWG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECDWR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3237EC	Samples
MAX3237ECPW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP237EC	Samples
MAX3237ECPWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP237EC	Samples
MAX3237ECPWRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MP237EC	Samples
MAX3237EIDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3237EI	Samples
MAX3237EIDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3237EI	Samples
MAX3237EIDW	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3237EI	Samples
MAX3237EIPW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP237EI	Samples
MAX3237EIPWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP237EI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

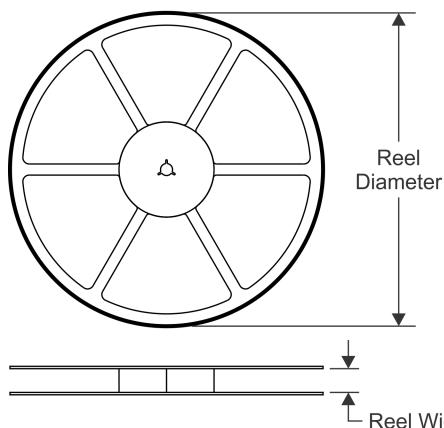
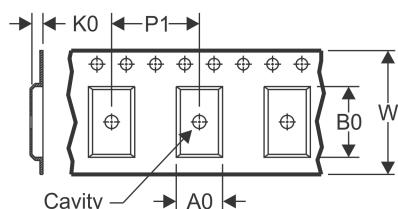
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

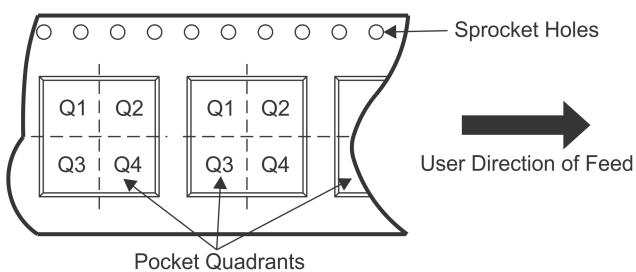
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3237ECDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
MAX3237ECDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
MAX3237ECPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
MAX3237EIDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
MAX3237EIPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

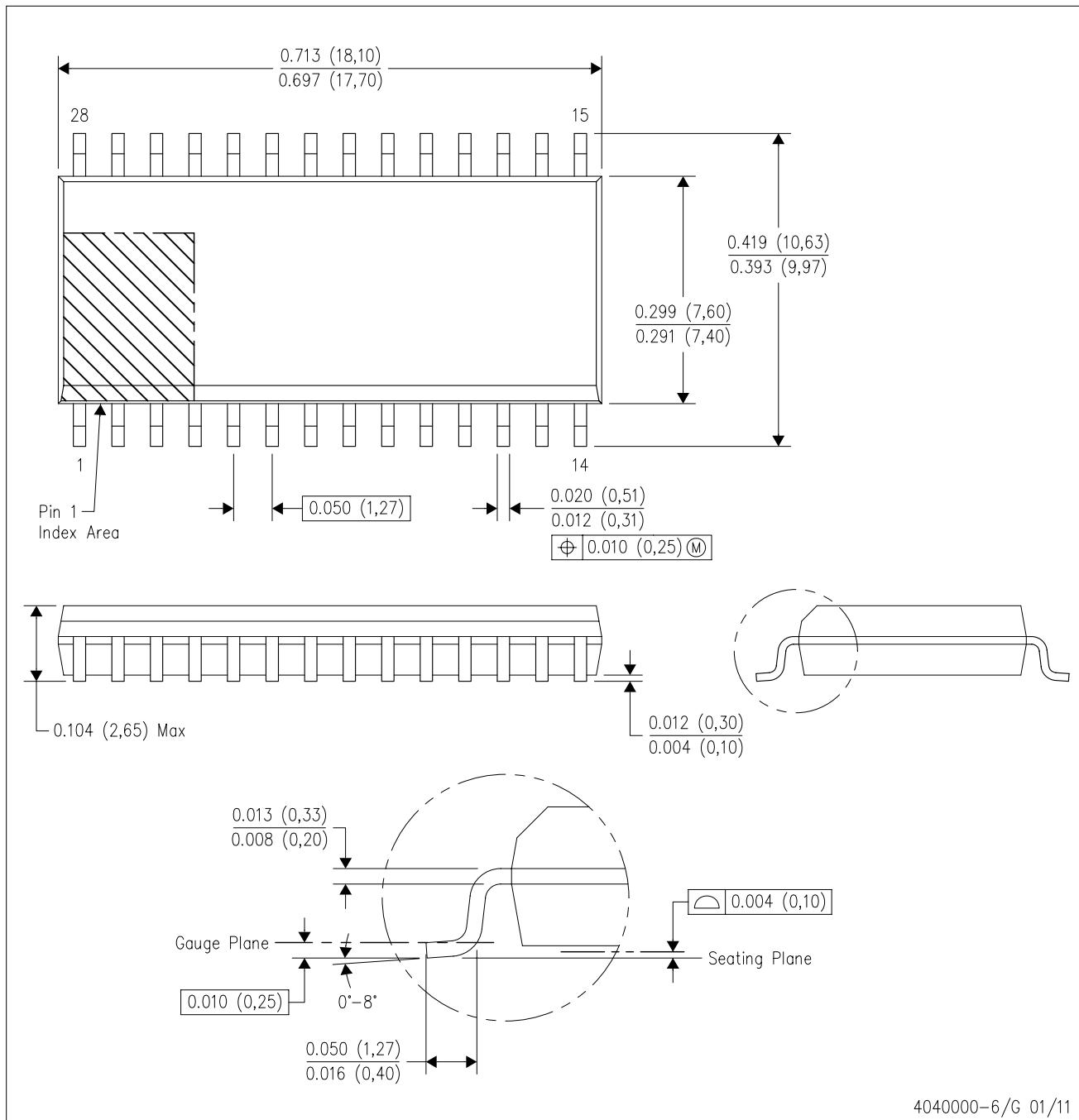
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3237ECDBR	SSOP	DB	28	2000	367.0	367.0	38.0
MAX3237ECDWR	SOIC	DW	28	1000	350.0	350.0	66.0
MAX3237ECPWR	TSSOP	PW	28	2000	367.0	367.0	38.0
MAX3237EIDBR	SSOP	DB	28	2000	367.0	367.0	38.0
MAX3237EIPWR	TSSOP	PW	28	2000	367.0	367.0	38.0

DW (R-PDSO-G28)

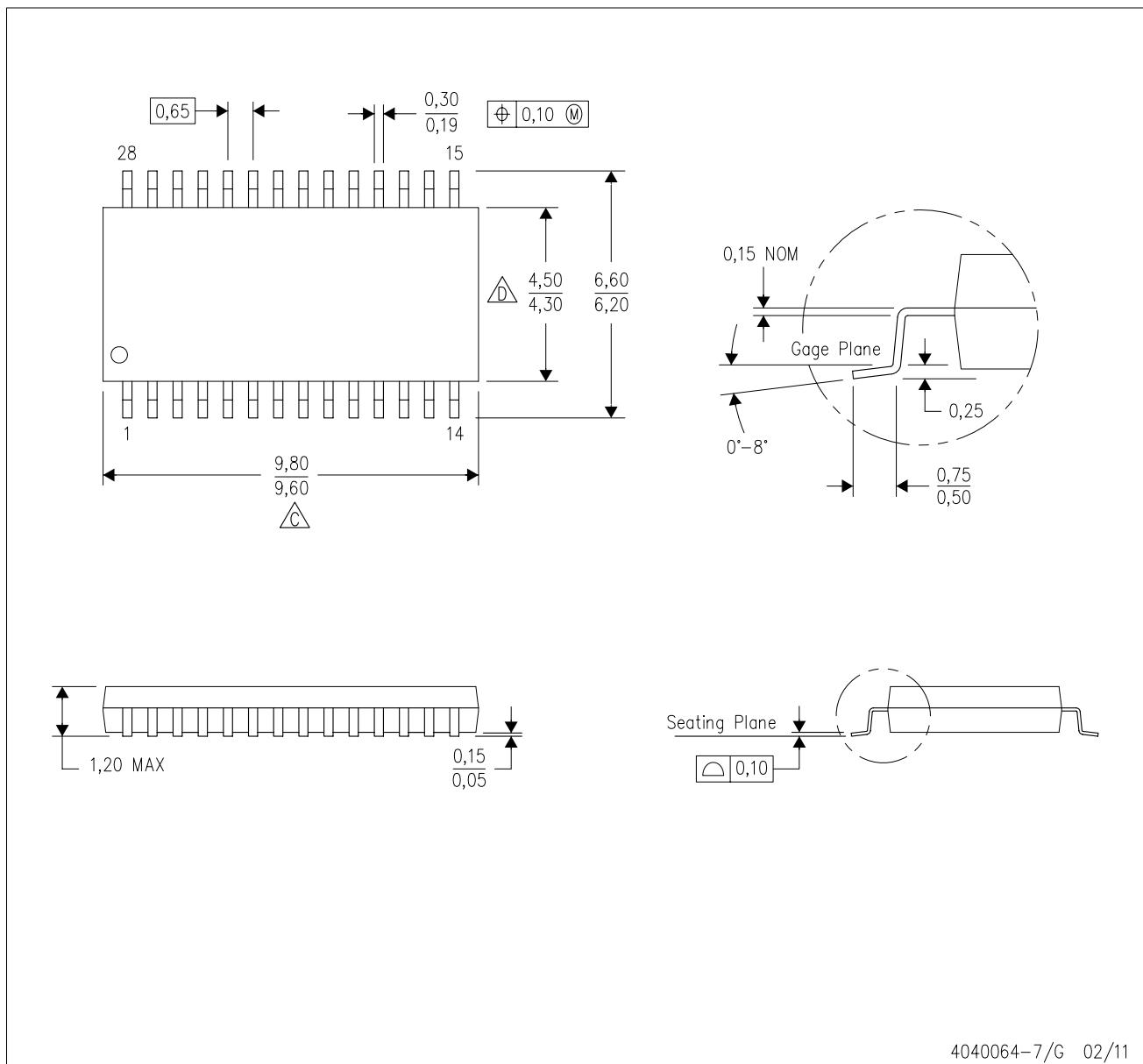
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
 - Falls within JEDEC MS-013 variation AE.

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



4040064-7/G 02/11

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

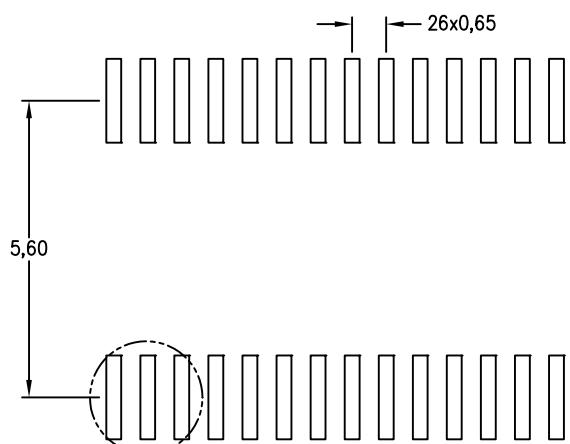
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

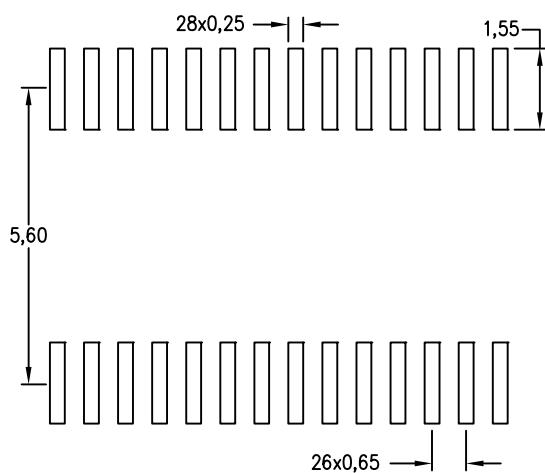
PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

Example Board Layout



Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).

Example
Non Soldermask Defined PadExample
Solder Mask Opening
(See Note E)

Pad Geometry

0,3
1,6
0,07 All Around

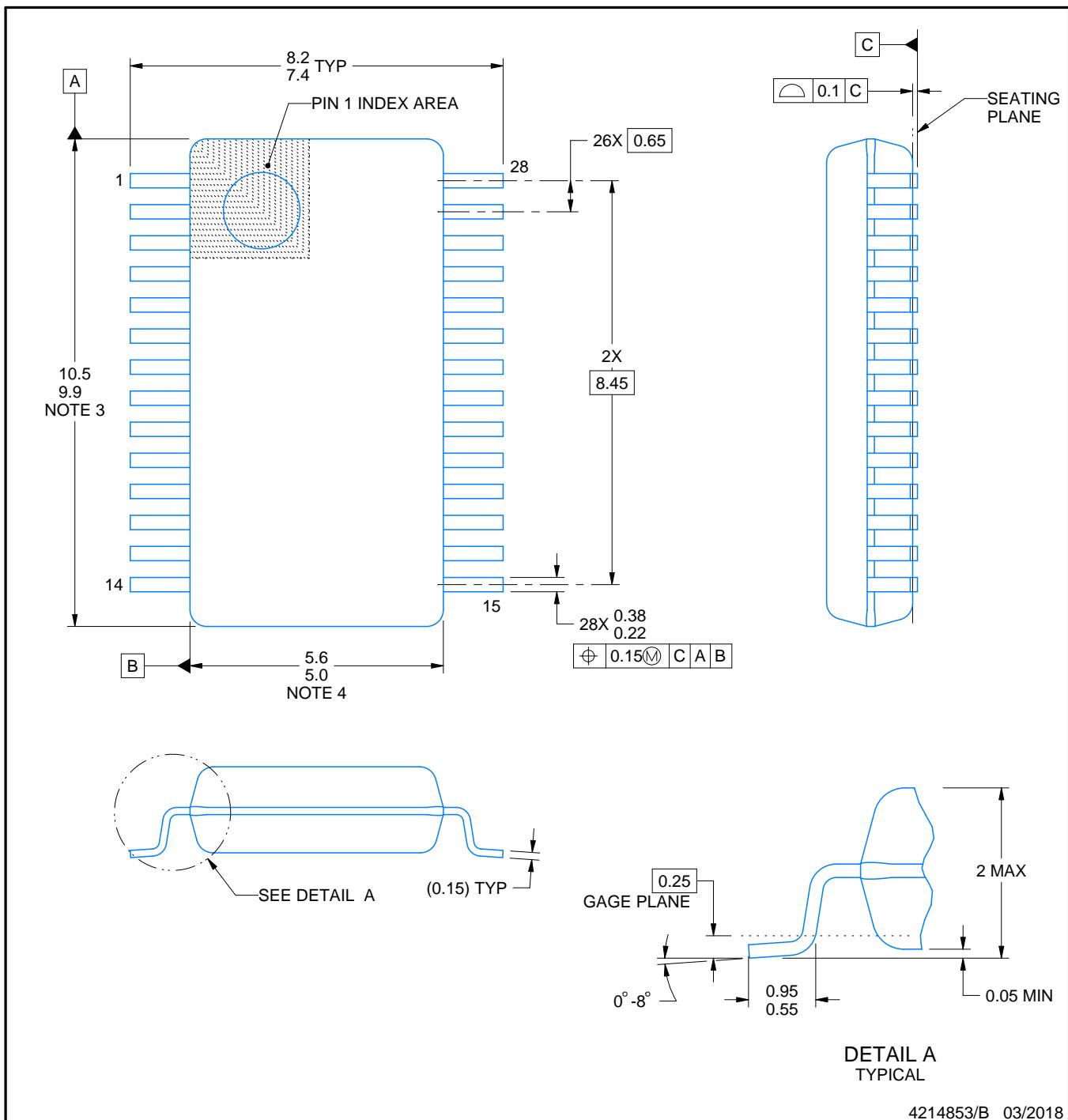
4211284-6/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate design.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

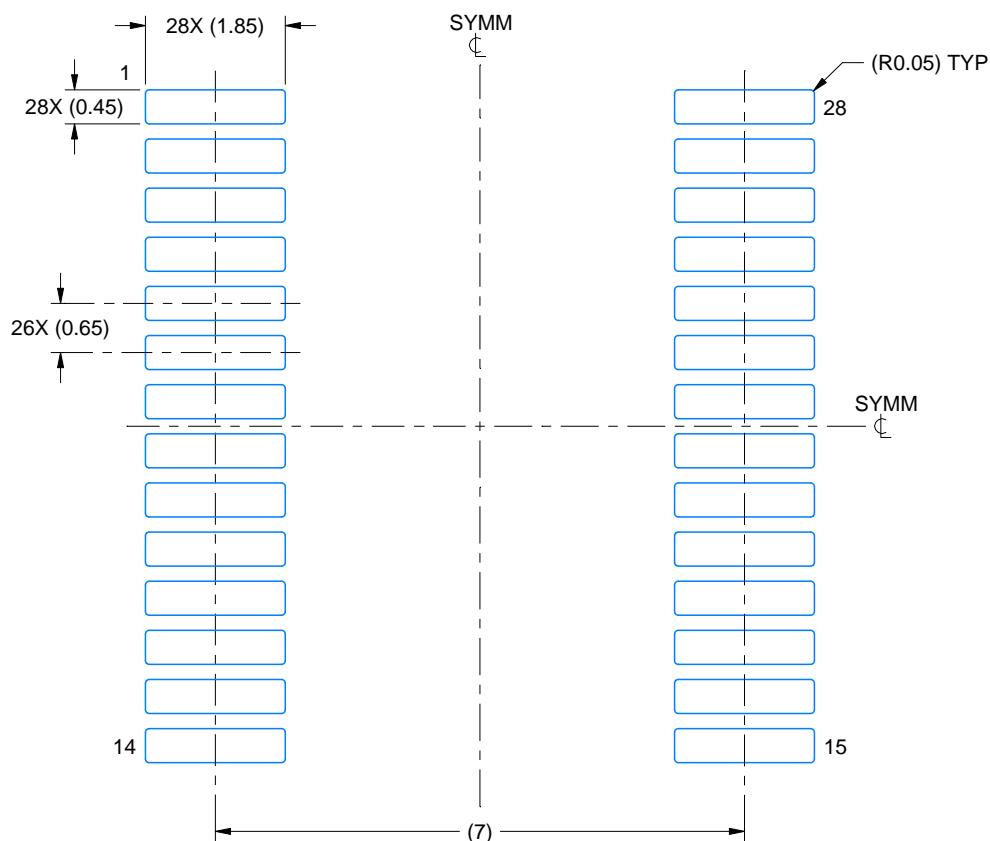
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

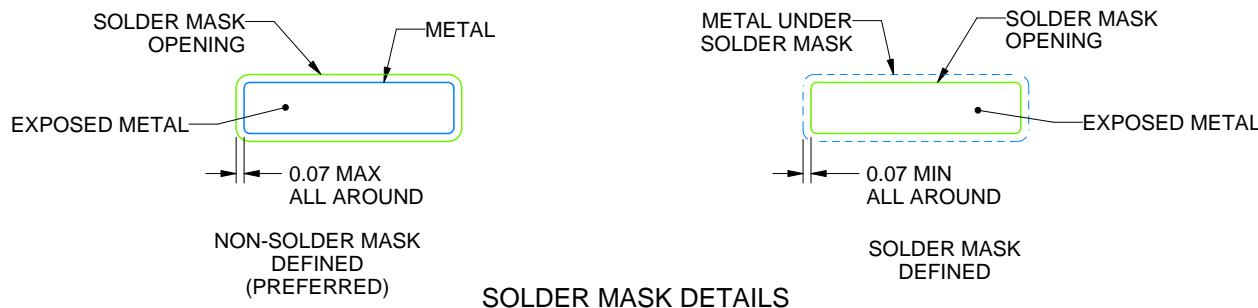
DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214853/B 03/2018

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

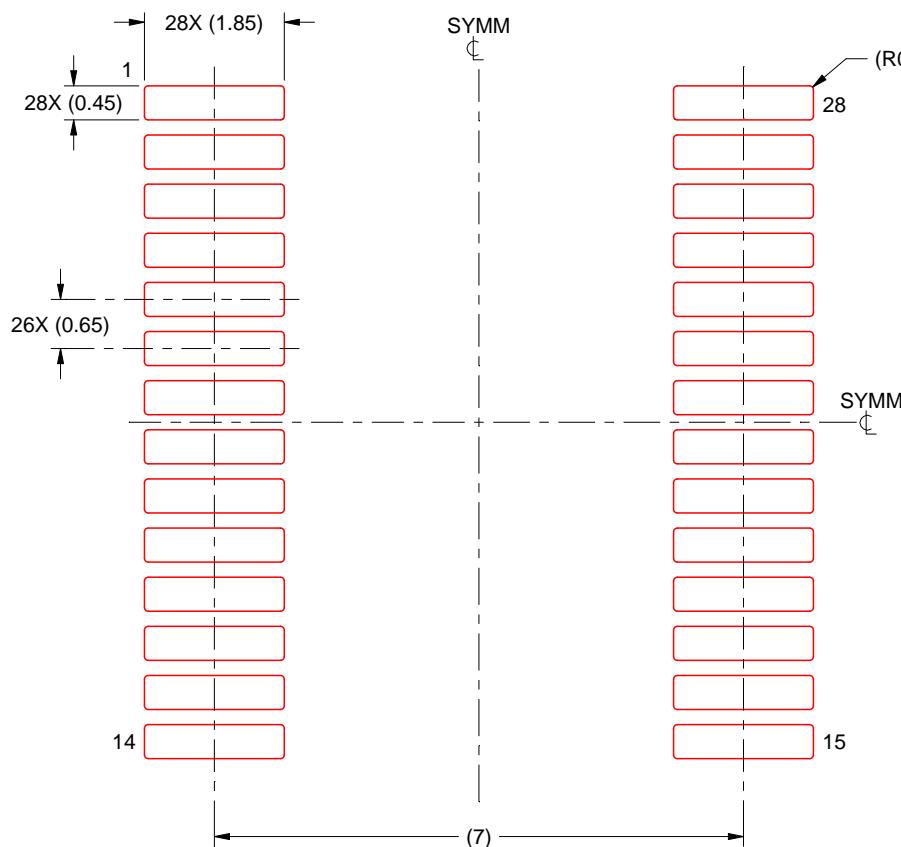
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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